T-1 3/4 (5mm) RIGHT ANGLE LED INDICATOR

Part Number: L-1503CB/1SRD

Super Bright Red

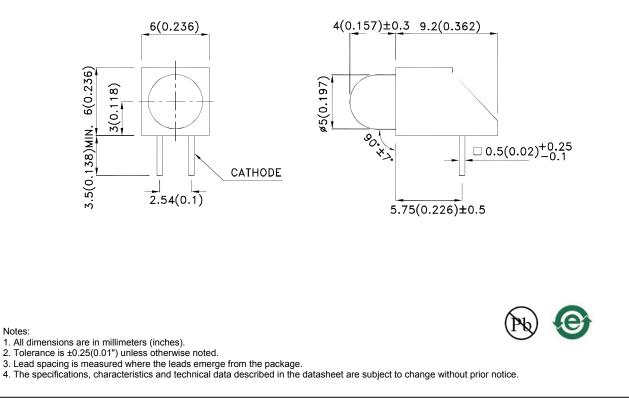
Features

- Low power consumption.
- Versatile mounting on P.C. board or panel.
- T-1 3/4 diameter flangeless package.
- Reliable and rugged.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

Description

The Super Bright Red source color devices are made with Gallium Aluminum Arsenide Red Light Emitting Diode.

Package Dimensions



SPEC NO: DSAC7366 APPROVED: WYNEC REV NO: V.10A CHECKED: Allen Liu DATE: JAN/16/2013 DRAWN: F.Cui PAGE: 1 OF 5 ERP: 1102000624

Selection Guide

Part No.		lv (mcd) [2] @ 20mA		Viewing Angle [1]	
			Min.	Тур.	201/2
L-1503CB/1SRD	Super Bright Red (GaAlAs)	Red Diffused	500	1000	60°
			*120	*260	

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Luminous intensity/ luminous Flux: +/-15%.
*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ. Max		Units	Test Conditions	
λpeak	Peak Wavelength	Super Bright Red	655		nm	IF=20mA	
λD [1]	Dominant Wavelength	Super Bright Red	640		nm	IF=20mA	
Δλ1/2	Spectral Line Half-width	Super Bright Red	20		nm	IF=20mA	
С	Capacitance	Super Bright Red	45		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	Super Bright Red	1.85	2.5	V	I⊧=20mA	
lr	Reverse Current	Super Bright Red		10	uA	VR = 5V	

Notes:

Wavelength: +/-1nm.
Forward Voltage: +/-0.1V.
Wavelength value is traceable to the CIE127-2007 compliant national standards.

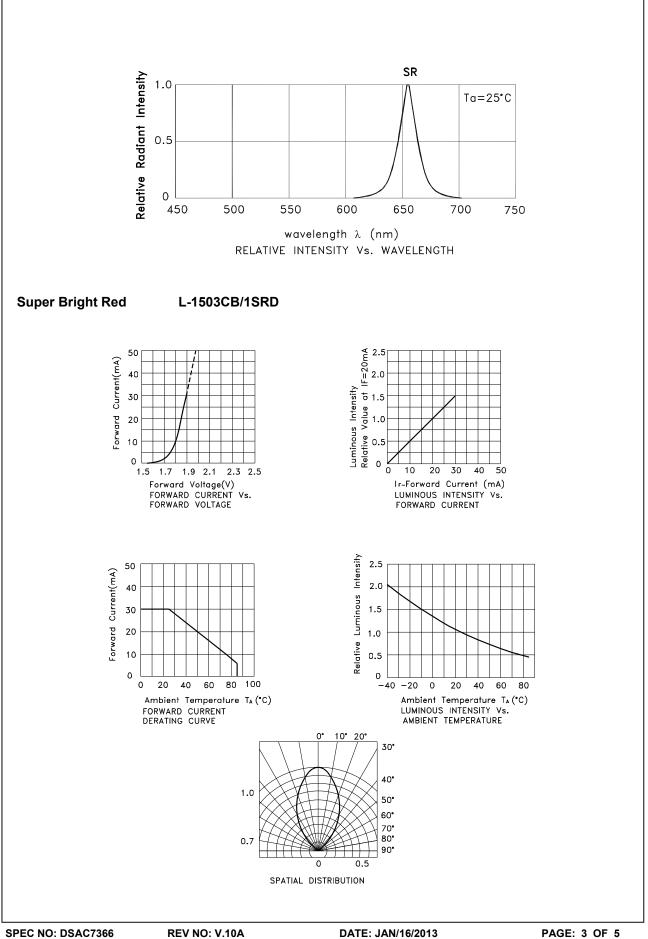
Absolute Maximum Ratings at TA=25°C

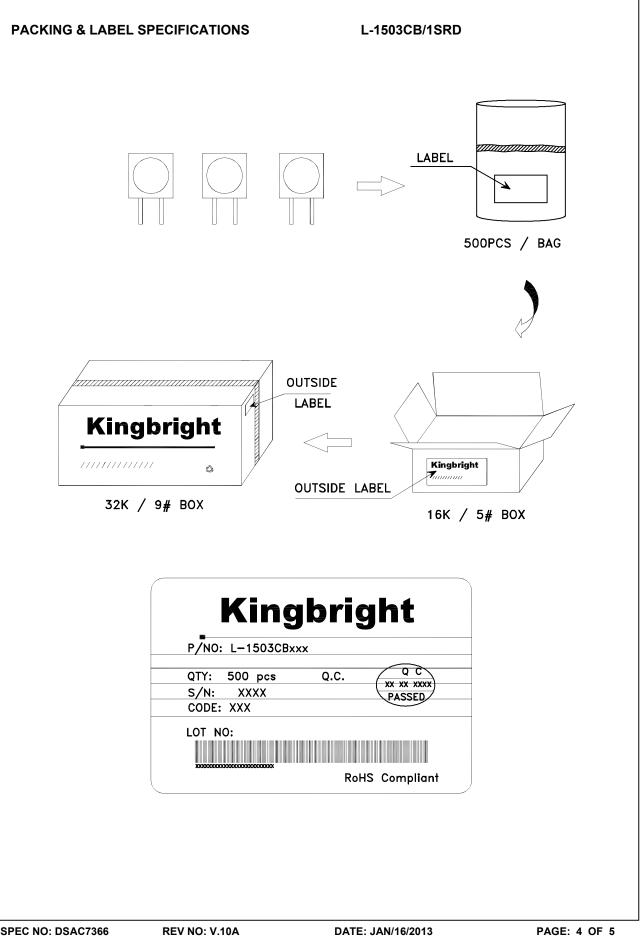
Super Bright Red		
75	mW	
30	mA	
155	mA	
5	V	
-40°C To +85°C		
260°C For 3 Seconds		
260°C For 5 Seconds		
	75 30 155 5 -40°C To +85°C 260°C For 3 Seconds	

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

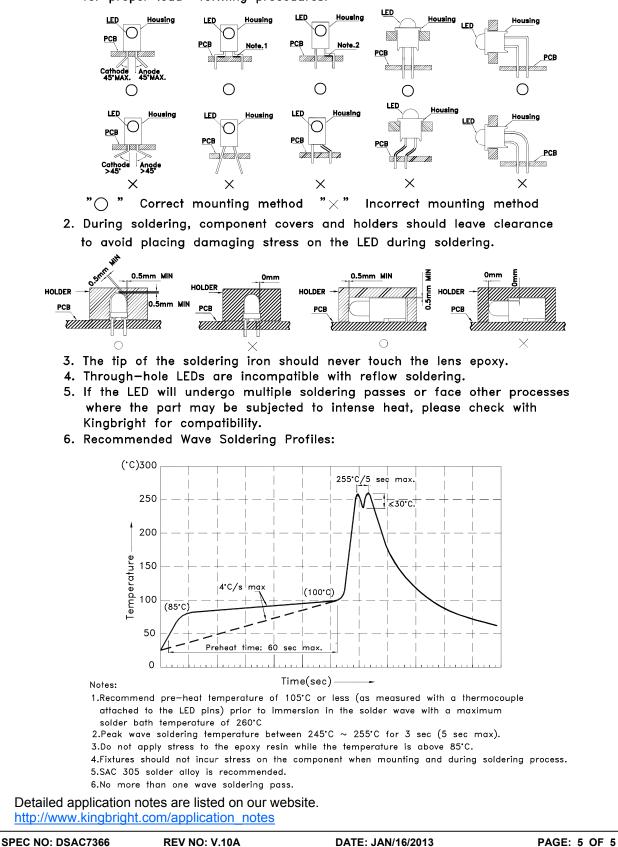
2. 2mm below package base.
3. 5mm below package base.





PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



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